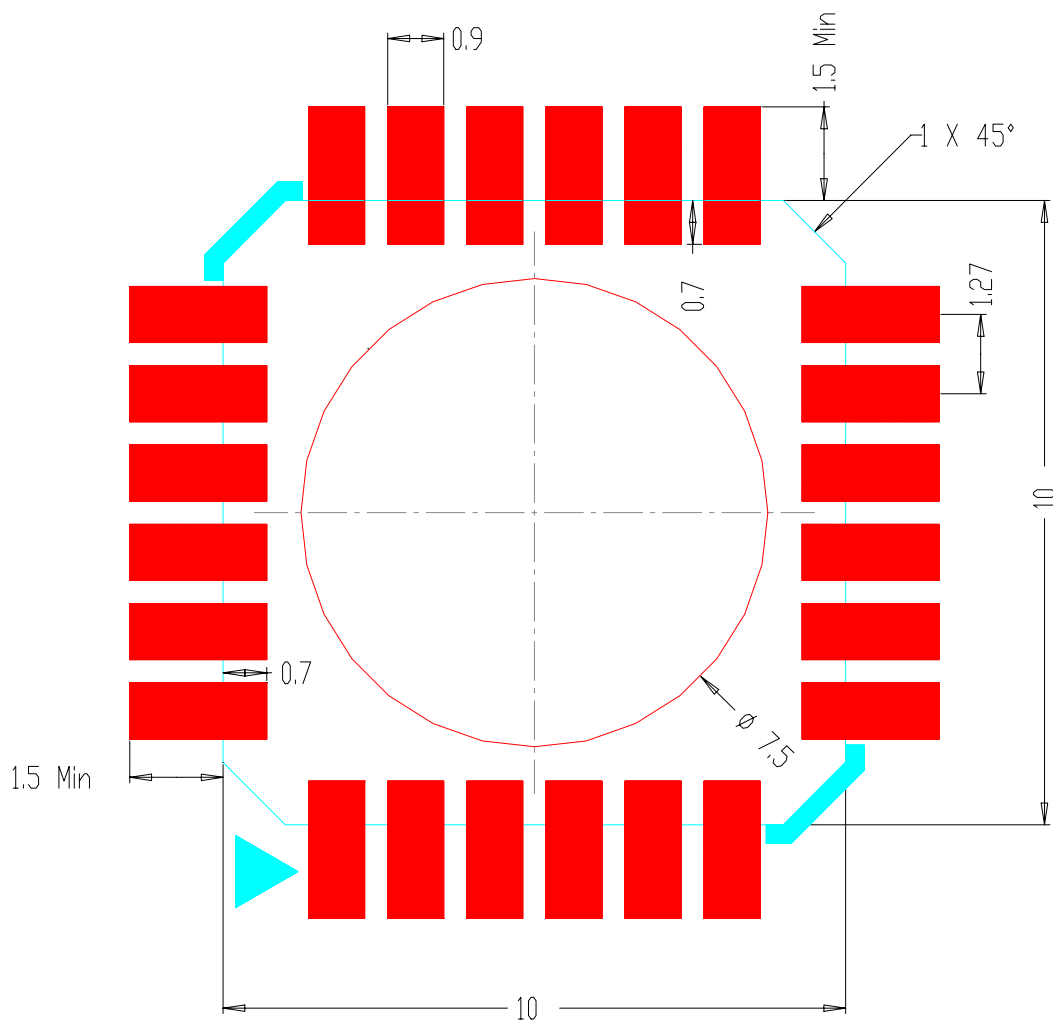


## RECOMMENDATIONS FOR SOLDERING OF DIGISENSOR'S MODULES

### *I. Footprint for the module:*

The following example is the footprint of MDS-02-0010 module, please follow this example to have the good footprint for your module.

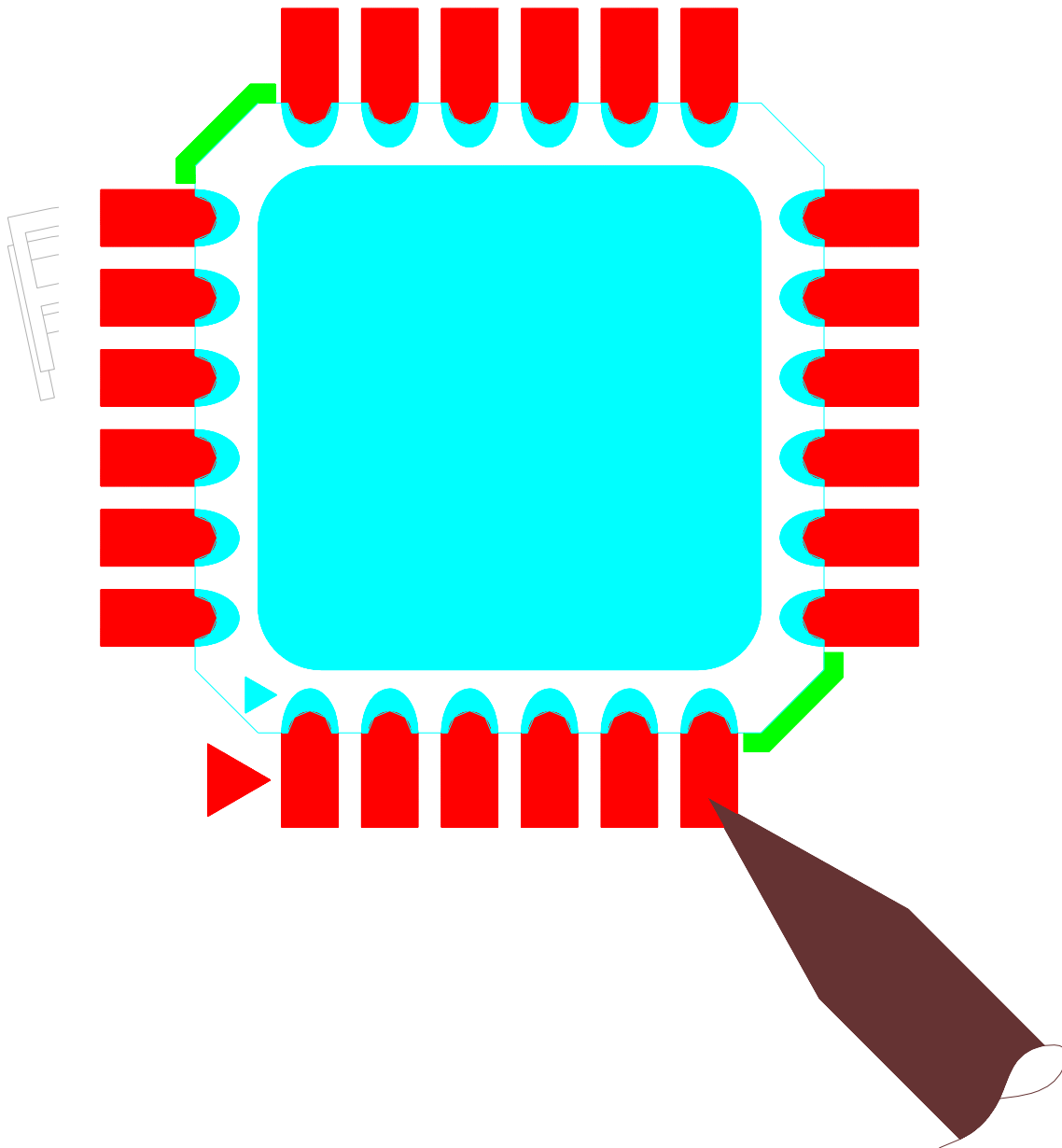


### *II. Hand soldering procedure:*

It is important not to heat too much the module during hand soldering. A large temperature above 250 deg C on the module could destroy it or create large offset to the pressure sensor. For a safe hand soldering of the module, follow strictly the hereunder mentioned recommendations:

Before starting soldering the module, please follow these notes:

- **The maximum power of the soldering iron is 25W with temperature control. Limit the temperature of the soldering iron tip to max. 300 deg C.**
- **Use ESD protection for worker and soldering iron.**
- **Use soldering lead with 2% of silver, wire diameter max. 0.5mm.**
- **Avoid to touch the pad of the module with the tip of the soldering iron. Heat the pad of the main pcb, touch this pad with the soldering lead wire and let the solder moving to the module pad.**





Soldering handling procedure:

1. Put lead on 1 pad of the main pcb.
2. Position the module correctly.
3. Put the soldering tip to the leading pad to fix the position of the module.
4. Solder all other pads of the module.

➤ **Do not wash the module with ultrasonic cleaning device.**

### ***III. Testing the module after soldering:***

It is recommended not to test the module right after soldering, wait for the module to be cool down to room temperature for at least 2 hours before testing the module.

PRELIMINARY